恒拓电子
HENGTUO ELECTRONICS

HT series

Photocoupler
Product Data Sheet

HT-817X

Spec No:HT-PC-817X-P-013-A1
Effective Date:07/04/2024

Zhejiang Hengtuo Electronic techlogy Co.,Ltd
298 Yongqing Road,Nanhu District,Jiaxing City,Zhengjiang Province
Tel:0573-82819382
https://hengtuo-elec.com

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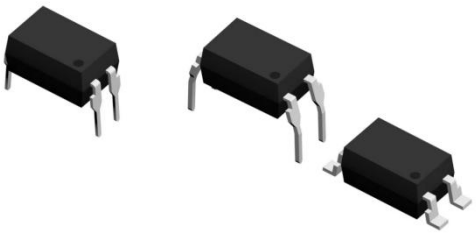
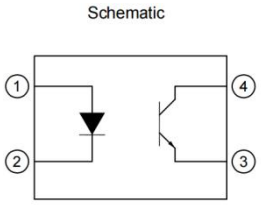
■ Package





Pin Configuration
1 Anode
2 Cathode
3 Emitter
4 Collector

■ Description

The HT-817X is a photoelectric coupler composed of light-emitting diode and phototransistor. It is packaged in a 4-pin DIP package and in wide-lead spacing and SMD opition.

■ Features

- Current transfer ratio(CTR : MIN. 50% at IF = 5mA, VCE = 5V)
- High input-output isolation voltage(Viso = 5,000Vrms)
- Operating Temperature: -55℃~110℃
- Safety approval
  (UL 1577，VDE DIN EN60747-5-5（VDE 0884-5），CQC11-471543-2022)
- RoHS
- MSL1

■ Applications

- Programmable controllers
- Switching power supply, intelligent meter
- Home appliances: such as air conditioners, fans, water heaters, etc

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■ Product Nomenclature

The product name is designated as below:

HT -817 X -X X- X X X- XX
① ② ③ ④ ⑤ ⑥ ⑦

Designation:

HT =Hengtuo Technology Co.,LTD.
817= Product Series
① = Lead form option(S1,M,NONE)(1)
② = CTR Rank(A,B,C,D)(2)
③ = Tape and Reel option(TP,TP1,NONE)(3)
④ = Lead frame Material(F,NONE)(4)
⑤ = VDE order option(fixed code "V")
⑥ = Halogen free option(fixed code"G")
⑦ = Customer code

Notes

1. Lead form option:

Symbol	Description
S1	DIP4-S1
M	DIP4-M
NONE	DIP4 Normal

2. CTR Rank:

Symbol	Description
A,B,C,D,...	CTR Rank
NONE	No Rank

3. Tape and Reel option:

Symbol	Description
TP&TP1	Tape and Reel Type
NONE	DIP Type

4. Lead frame Material

Symbol	Description
F	Iron
NONE	Copper

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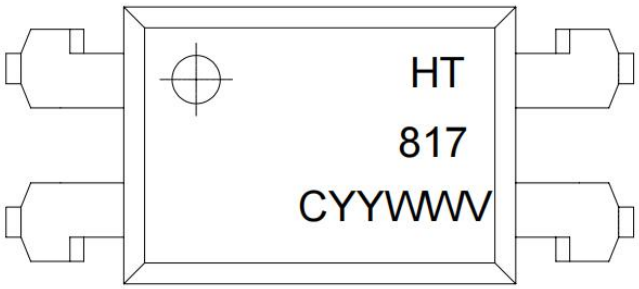
■ Marking Information



Designation:

HT	denotes Hengtuo
817	denotes Device
C	denotes CTR Rank
YY	denotes year code
WW	denotes week code
V	denotes VDE

■ Maximum Ratings

Parameter		Symbol	Values	Unit
Input	Forward Current	I_F	50	mA
	Reverse Voltage	V_R	6	V
	Power Dissipation	P	70	MW
	Peak Forward Current (100μs pulse, 100Hz)	I_{FP}	1	A
	Thermal Resistance Junction-Ambient	R_{thJ-A}	325	°C/W
	Thermal Resistance Junction-Case	R_{thJ-C}	200	°C/W
Output	Collector - Emitter Voltage	V_{CEO}	80	V
	Emitter - Collector Voltage	V_{ECO}	6	V
	Collector Current	I_C	50	mA
	Collector Power Dissipation	P_C	150	mW
Operating temperature range		T_{op}	–55 ~ 110	°C
Storage temperature range		T_{stg}	–55 ~ 125	°C
Total Power consumption		P(W)	200	mW
Isolation Voltage(1)		V_{ISO}	5000	Vrms
Soldering Temperature(2)		T_{SOL}	260	°C

Notes:
(1). AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.
(2).For 10 seconds

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■ Electronic Optical Characteristics

(TA = 25°C)

Parameter		Symbol	Min.	Typ.	Max.	Unit	Conditon
Input	Forward Voltage	V_F	-	1.2	1.4	V	I_F=20mA
	Reverse Current	I_R	-	-	10	μA	V_R=4V
	Terminal Capacitance	C_t	-	30	250	pF	V=0, f=1KHz
Output	Collector Dark Current	I_{CEO}	-	-	100	nA	VCE=20V, IF=0
	Collector-Emitter Breakdown Voltage	BV_{CEO}	80			V	IC=0.1mA, IF=0
	Emitter-Collector Breakdown Voltage	BV_{ECO}	6			V	IE=10μA, IF=0
Collector-Emitter Saturation Voltage		$V_{CE(sat)}$		0.1	0.2	V	IF=20mA, IC=1mA
Isolation Resistance		R_{iso}	5×10^{10}	1×10^{11}	-	Ω	DC500V, 40 ~ 60% R.H.
Floating Capacitance		Cf		0.6	1	pF	V=0, f=1MHz
Cut-off Frequency		fc		80		kHz	VCE=5V, IC=2mA RL=100Ω,-3dB
Response Time (Rise)		tr		4	18	μs	VCE=2V, IC=2mA RL=100Ω,
Response Time (Fall)		tf		3	18	μs	

■ Rank Table Of Current Transfer Ratio

(CTR=IC/IF x 100%)

Rank Code	Symbol	Min	Max	Conditon
NONE	CTR	50	600	IF=5mA, VCE=5V, Ta=25°C
A		80	160	
B		130	260	
C		200	400	
D		300	600	

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■ Characteristics Curves

Fig.1 Allowable Forward Current
VS Ambient Temperature

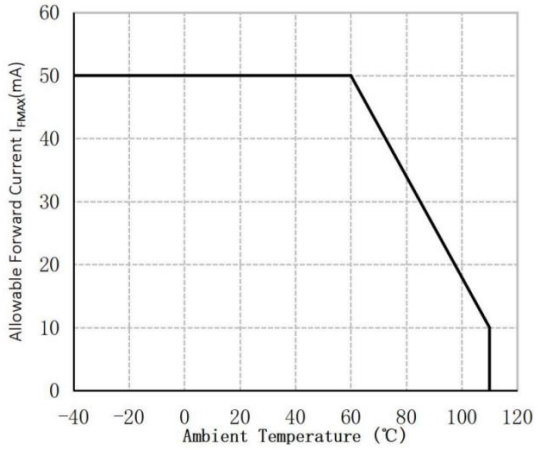


Fig.2 Allowable collector power disspation
VS Ambient Temperature(℃)

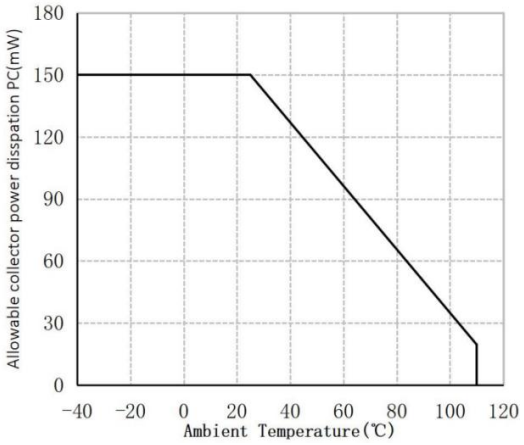


Fig.3 Relative Current Transfer Ratio
vs. Forward Current

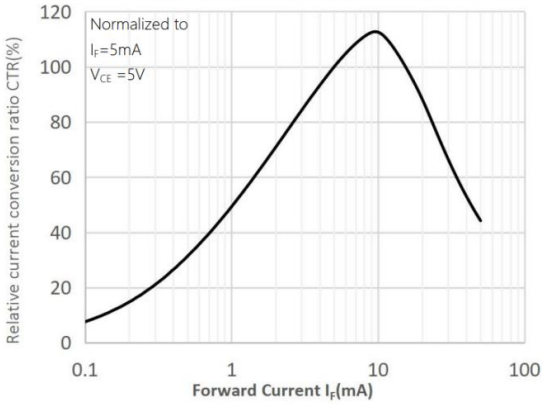


Fig4 Forward Current vs. ForwardVoltage

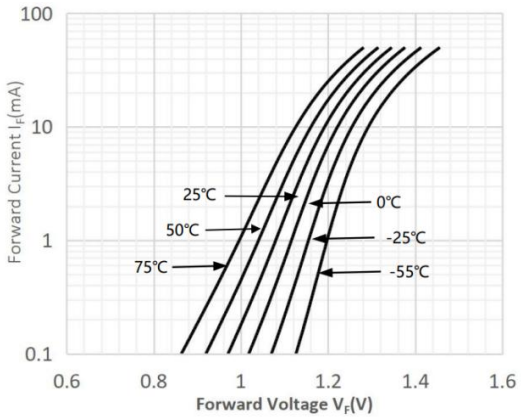


Fig.5 Collector Current vs. Collector-emitter Voltage

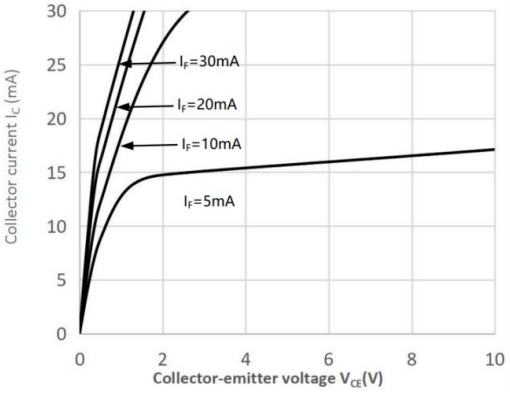


Fig.6 Relative Current Transfer Ratio
vs.Ambient Temperature

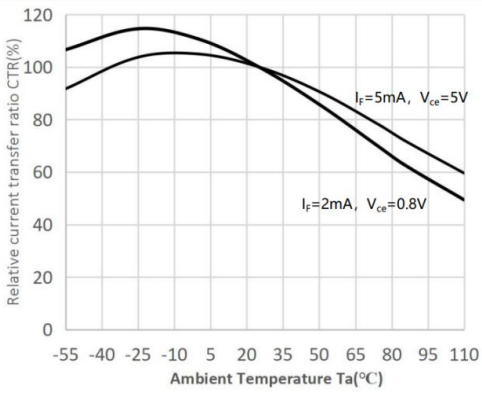


Fig.7 Collector-emitter Saturation Voltage vs. Ambient Temperature

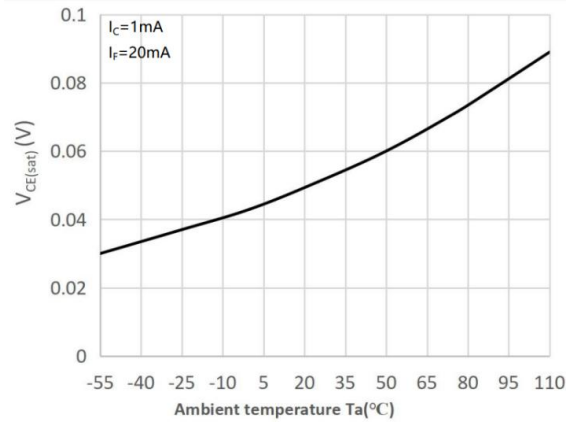


Fig.8 Collector Dark Current vs Ambient Temperature

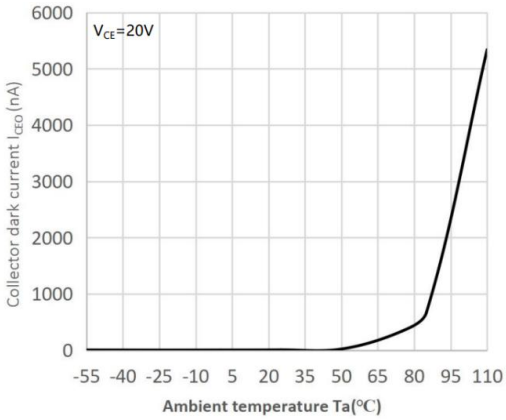


Fig.9 Response Time vs. Load Resistance

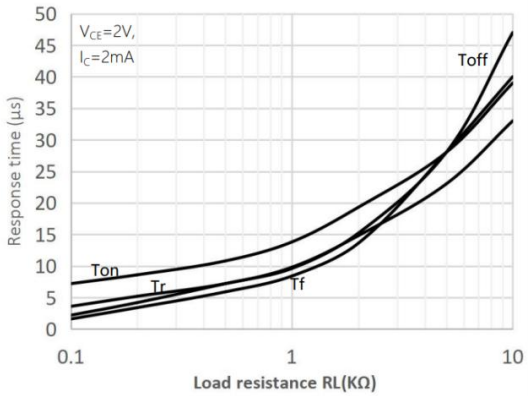


Fig.10 Frequency Response

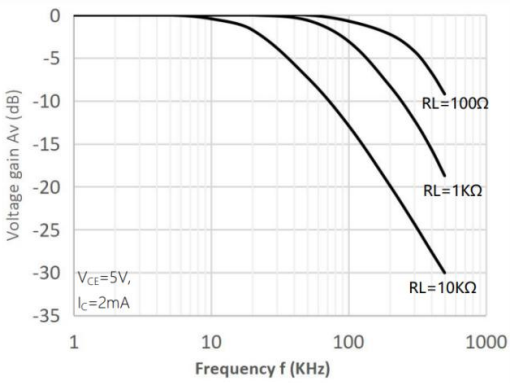


Fig.11 Collector-emitter Saturation Voltage vs Forward Current

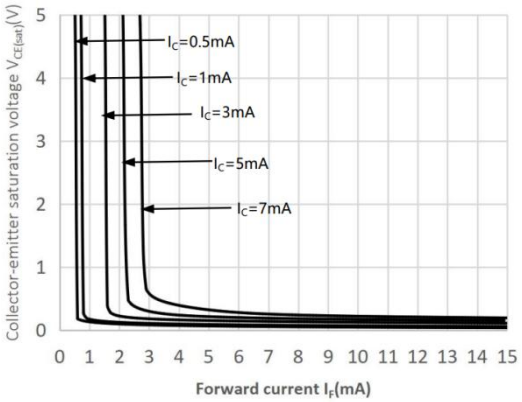
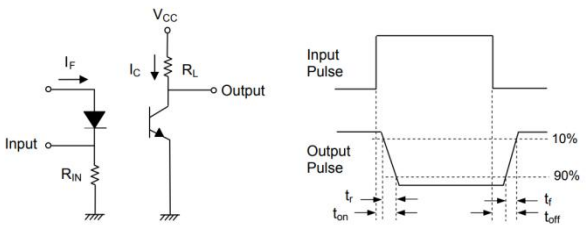


Fig.12 Switching Time Test Circuit & Waveforms



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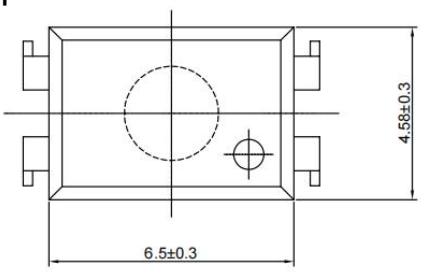
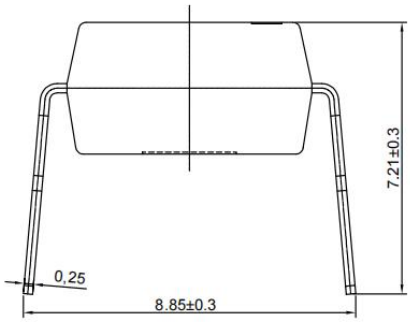
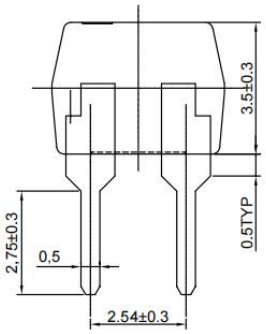
■ Outline Dimension

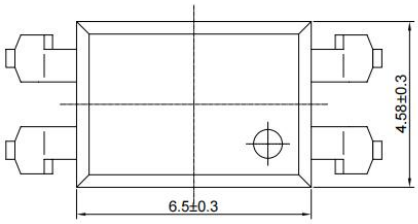
DIP Normal Type:

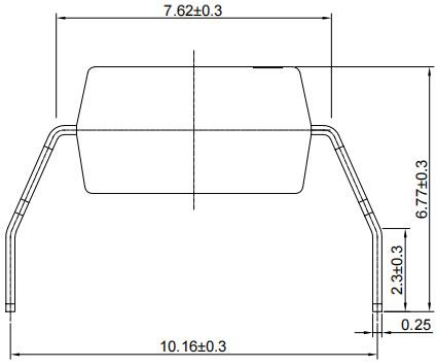


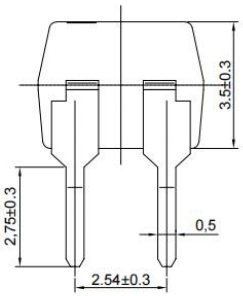




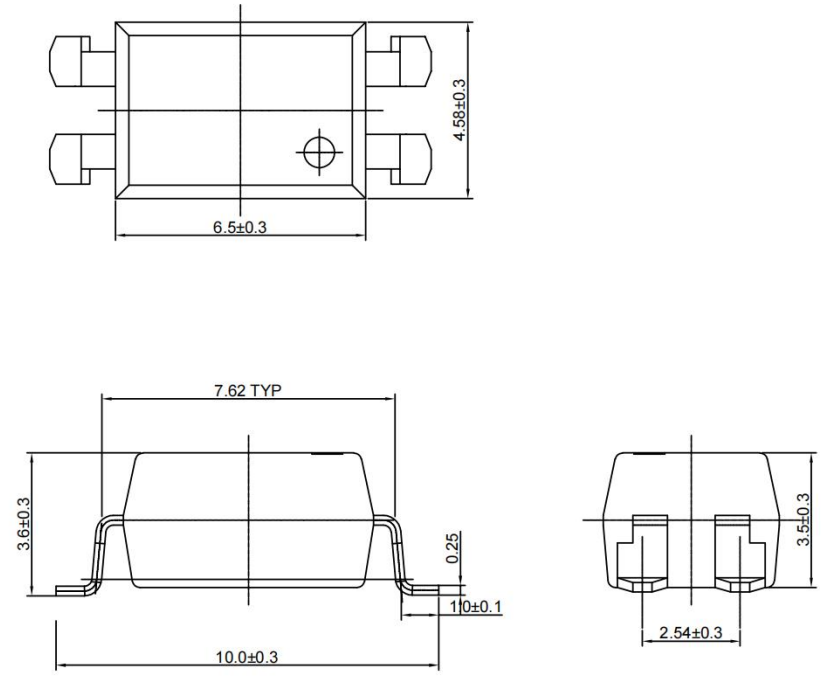
DIP M Type:







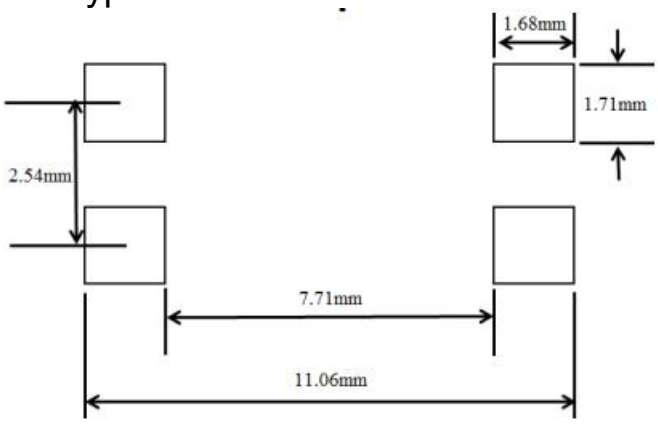
DIP S1 Type:



Unit: mm
Tolerance: ±0.1mm

■ Recommended solder pad Design

For S1 type:



Unit: mm
Tolerance: ±0.1mm

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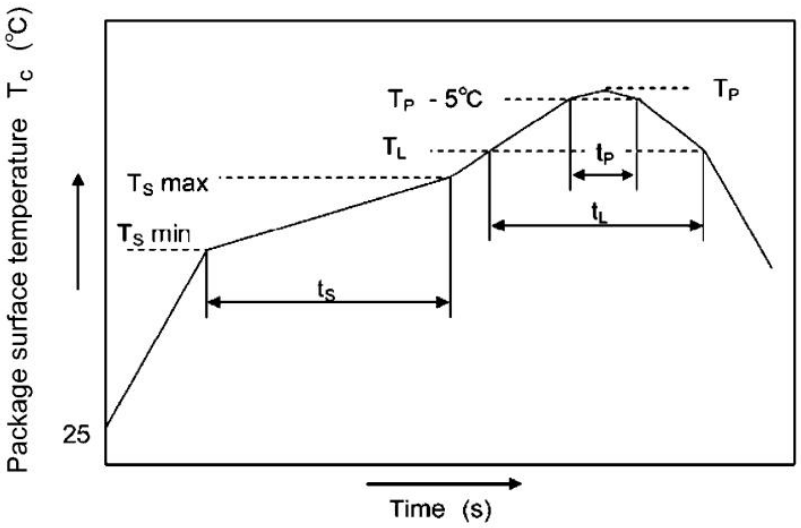
■ Temperature Profile Of Soldering

1. IR Reflow soldering

(JEDEC-STD-020D compliant)

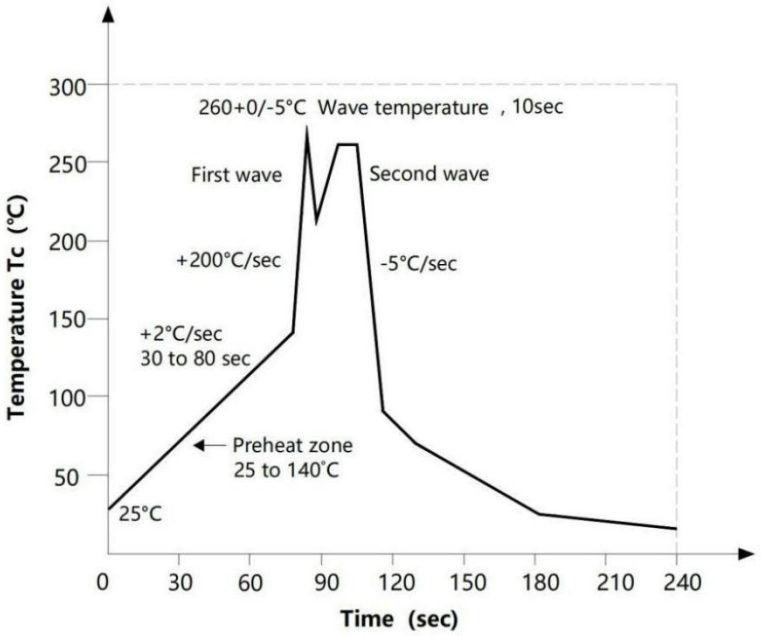
Profile item	Conditon
Preheat	
-Temperature Min (TSmin)	150°C
-Temperature Max (TSmax)	200°C
-Time (min to max) (ts)	90±30 sec
Soldering zone	
-Temperature (TL)	217°C
-Time (t_L)	60-150 sec
Peak Temperature (TP)	260°C
-Time (TP-5℃to TP) (ts)	30 sec
Ramp-up rate	3°C / sec max
Ramp-down rate	3~6°C/ sec



Notes:
One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

2. Wave soldering (JEDEC22A111 compliant)

One time soldering is recommended within the condition.
Temperature:260+0/-5˚C.
Time:10 sec.
Preheat temperature:25 to 140˚C.
Preheat time:30 to 80 sec.



3. Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.
Temperature: 380+0/-5˚C
Time: 3 sec max.

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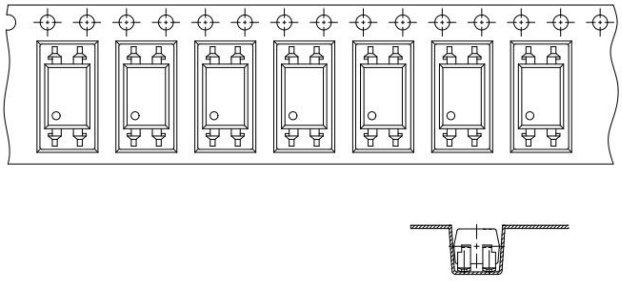
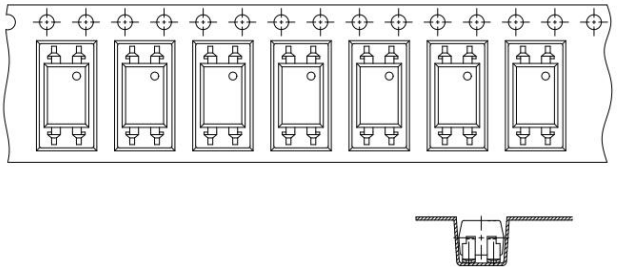
■ Packing

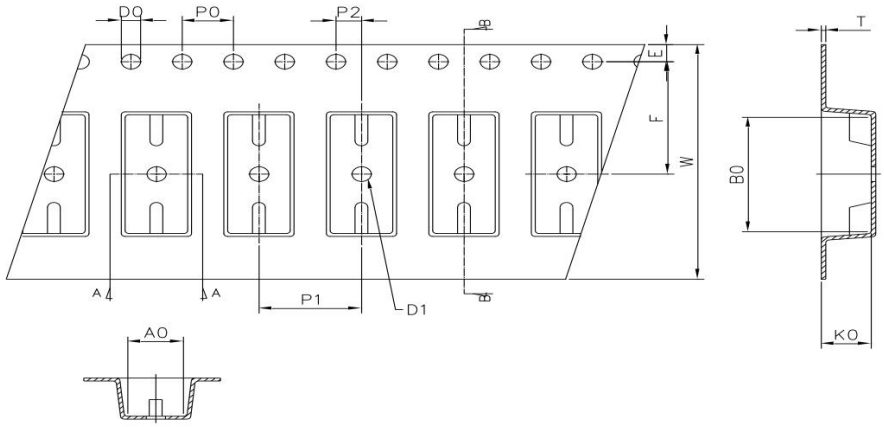
1. Tape and Reel

Option TP:



Option TP1:





Deminsion/mm	W	E	F	P0	P1	P2
Packagetype:DIP S1	16±0.2	1.75±0.1	7.5±0.1	4±0.1	8±0.1	2±0.1

Deminsion/mm	A0	B0	D0	D1	K0	T
Packagetype:DIP S1	4.6±0.1	10.4±0.1	1.5±0.1	1.5±0.1	4.2±0.1	0.4±0.1

Packagetype:DIP S1	Reel	Inner carton	Outer carton
QTY/PCS	2K/reel	4K(2 reels)	40K

2. Tape and Tube

Packagetype:Normal&M	Tube	Inner carton	Outer carton
QTY/PCS	100	5K(50 Tubes)	50K

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■ Attention:

- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any ”specific” application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.